

3.3 V Zero Delay Buffer

Features

- Zero input-output propagation delay, adjustable by capacitive load on FBK input
- Multiple configurations, see Available CY2308 Configurations on page 4 for more details
- Multiple low skew outputs
- Two banks of four outputs, three-stateable by two select inputs
- 10 MHz to 133 MHz operating range
- 75 ps typical cycle-to-cycle jitter (15 pF, 66 MHz)
- Space saving 16-pin 150 mil SOIC package or 16-pin TSSOP
- 3.3 V operation
- Industrial temperature available

Functional Description

The CY2308 is a 3.3 V Zero Delay Buffer designed to distribute high speed clocks in PC, workstation, datacom, telecom, and other high performance applications.

The part has an on-chip PLL that locks to an input clock presented on the REF pin. The PLL feedback is driven from external FBK pin, so user has flexibility to choose any one of the outputs as feedback input and connect it to FBK pin. The input-to-output skew is less than 250 ps and output-to-output skew is less than 200 ps.

The CY2308 has two banks of four outputs each that is controlled by the select inputs as shown in the table Select Input Decoding on page 3. If all output clocks are not required, Bank B is three-stated. The input clock is directly applied to the output for chip and system testing purposes by the select inputs.

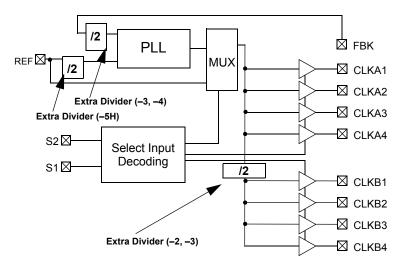
The CY2308 PLL enters a power down state when there are no rising edges on the REF input. In this mode, all outputs are three-stated and the PLL is turned off resulting in less than 25 μ A of current draw. The PLL shuts down in two additional cases as shown in the table Select Input Decoding on page 3.

Multiple CY2308 devices accept the same input clock and distribute it in a system. In this case, the skew between the outputs of two devices is less than 700 ps.

The CY2308 is available in five different configurations as shown in the table Available CY2308 Configurations on page 4.

- The CY2308-1 is the base part where the output frequencies equal the reference if there is no counter in the feedback path. The CY2308-1H is the high drive version of the -1 and rise and fall times on this device are much faster.
- The CY2308-2 enables the user to obtain 2x and 1x frequencies on each output bank. The exact configuration and output frequencies depend on the user's selection of output that drives the feedback pin.
- The CY2308-3 enables the user to obtain 4x and 2x frequencies on the outputs.
- The CY2308-4 enables the user to obtain 2x clocks on all outputs. Thus, the part is extremely versatile and is used in a variety of applications.
- The CY2308-5H is a high drive version with REF/2 on both banks.

Logic Block Diagram





Contents

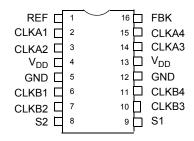
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Pinouts

Figure 1. 16-pin SOIC pinout (Top View)



Pin Definitions

16-pin SOIC

Pin	Signal	Description
1	REF [1]	Input reference frequency
2	CLKA1 [2]	Clock output, Bank A
3	CLKA2 ^[2]	Clock output, Bank A
4	V_{DD}	Power supply voltage
5	GND	Power supply ground
6	CLKB1 [2]	Clock output, Bank B
7	CLKB2 ^[2]	Clock output, Bank B
8	S2 ^[3]	Select input, bit 2
9	S1 ^[3]	Select input, bit 1
10	CLKB3 ^[2]	Clock output, Bank B
11	CLKB4 ^[2]	Clock output, Bank B
12	GND	Power supply ground
13	V_{DD}	Power supply voltage
14	CLKA3 ^[2]	Clock output, Bank A
15	CLKA4 [2]	Clock output, Bank A
16	FBK	PLL feedback input

Select Input Decoding

S2	S1	CLOCK A1-A4	CLOCK B1-B4	Output Source	PLL Shutdown
0	0	Tri-state	Tri-state	PLL	Y
0	1	Driven	Tri-state	PLL	N
1	0	Driven [4]	Driven [4]	Reference	Y
1	1	Driven	Driven	PLL	N

- 1. Weak pull down.
 2. Weak pull down on all outputs.
 3. Weak pull ups on these inputs.
 4. Outputs inverted and PLL bypass mode for 2308-2 and 2308-3, S2 = 1 and S1 = 0.

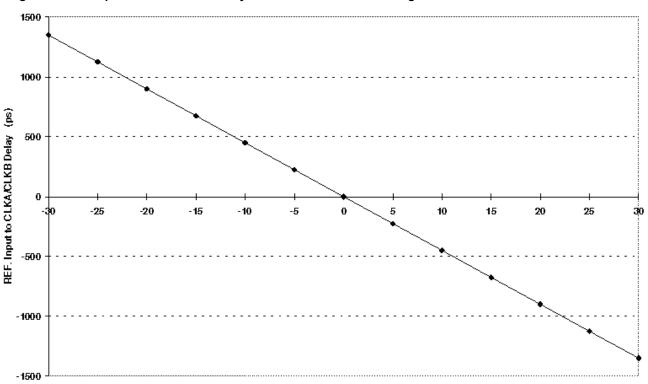


Available CY2308 Configurations

Device	Feedback From [5]	Bank A Frequency	Bank B Frequency
CY2308-1	Bank A or Bank B	Reference	Reference
CY2308-1H	Bank A or Bank B	Reference	Reference
CY2308-2	Bank A	Reference	Reference / 2
CY2308-2	Bank B	2 × Reference	Reference
CY2308-3	Bank A	2 × Reference	Reference [6]
CY2308-3	Bank B	4 × Reference	2 × Reference
CY2308-4	Bank A or Bank B	2 × Reference	2 × Reference
CY2308-5H	Bank A or Bank B	Reference / 2	Reference / 2

Zero Delay and Skew Control

Figure 2. REF. Input to CLKA/CLKB Delay Versus Difference in Loading between FBK Pin and CLKA/CLKB Pins



Output Load Difference: FBK Load - CLKA/CLKB Load (pF)

To close the feedback loop of the CY2308, the user has to connect any one of the eight available output pins to FBK pin. The output driving the FBK pin drives a total load of 7 pF plus any additional load that it drives. The relative loading of this output to the remaining outputs adjusts the input-output delay as shown in the Figure 2.

For applications requiring zero input-output delay, all outputs including the one providing feedback is equally loaded.

If input-output delay adjustments are required, use the Zero Delay and Skew Control graph to calculate loading differences between the feedback output and remaining outputs.

For zero output-output skew, outputs are loaded equally. For further information on using CY2308, refer to the application note CY2308: Zero Delay Buffer-AN1234.

- 5. User has to select one of the available outputs that drive the feedback pin and need to connect selected output pin to FBK pin externally.
- 6. Output phase is indeterminant (0 ° or 180 ° from input clock). If phase integrity is required, use CY2308-2.



Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Supply voltage to ground potential-0.5 V to +7.0 V DC input voltage (except REF)-0.5 V to V_{DD} + 0.5 V

DC input voltage REF	–0.5 V to 7 V
Storage temperature	–65 °C to +150 °C
Junction temperature	150 °C
Static discharge voltage (MIL-STD-883, Method 3015)	>2000 V

Operating Conditions for Commercial Temperature Devices

Parameter	Description	Min	Max	Unit
V_{DD}	Supply voltage	3.0	3.6	V
T _A	Operating temperature (ambient temperature)	0	70	°C
C _L	Load capacitance, below 100 MHz	_	30	pF
	Load capacitance, from 100 MHz to 133 MHz	_	15	pF
C _{IN}	Input capacitance [7]	_	7	pF
t _{PU}	Power up time for all V_{DD} 's to reach minimum specified voltage (power ramps must be monotonic)	0.05	50	ms

Electrical Characteristics for Commercial Temperature Devices

Parameter	Description	Test Conditions	Min	Max	Unit
V _{IL}	Input LOW voltage		-	0.8	V
V _{IH}	Input HIGH voltage		2.0	-	V
I _{IL}	Input LOW current	V _{IN} = 0 V	_	50.0	μΑ
I _{IH}	Input HIGH current	$V_{IN} = V_{DD}$	_	100.0	μΑ
V _{OL}	Output LOW voltage [8]	I _{OL} = 8 mA (-1, -2, -3, -4) I _{OL} = 12 mA (-1H, -5H)	-	0.4	V
V _{OH}	Output HIGH voltage [8]	I _{OH} = -8 mA (-1, -2, -3, -4) I _{OH} = -12 mA (-1H, -5H)	2.4	-	V
I _{DD} (PD mode)	Power down supply current	REF = 0 MHz	-	12.0	μА
I _{DD}	Supply current	Unloaded outputs, 100 MHz REF, select inputs at	_	45.0	mA
		V _{DD} or GND	-	70.0 (-1H, -5H)	mA
		Unloaded outputs, 66 MHz REF (-1, -2, -3, -4)	_	32.0	mA
		Unloaded outputs, 33 MHz REF (-1, -2, -3, -4)		18.0	mA

Notes

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^{7.} Applies to both Ref clock and FBK.

^{8.} Parameter is guaranteed by design and characterization. Not 100% tested in production.



Switching Characteristics for Commercial Temperature Devices

Parameter [9]	Description	Test Conditions	Min	Тур	Max	Unit
F _{in}	Input frequency	_	10	-	133.3	MHz
t ₁	Output frequency	30 pF load	10	-	100 (-1, -2, -3, -4) 66.67 (-5H)	MHz
t ₁	Output frequency	20 pF load, -1H, -5H devices	10	_	133.3 (-1H) 66.67 (-5H)	MHz
t ₁	Output frequency	15 pF load, -1, -2, -3, -4 devices	10	_	133.3	MHz
t _{PD}	Duty cycle ^[9] = $t_2 \div t_1$ (-1, -2, -3, -4, -1H, -5H)	Measured at 1.4 V, F _{OUT} = 66.66 MHz, 30 pF load	40.0	50.0	60.0	%
t _{PD}	Duty cycle ^[9] = t ₂ ÷ t ₁ (-1, -2, -3, -4, -1H, -5H)	Measured at 1.4 V, F _{OUT} < 50 MHz, 15 pF load	45.0	50.0	55.0	%
t ₃	Rise time ^[9] (-1, -2, -3, -4)	Measured between 0.8 V and 2.0 V, 30 pF load	_	_	2.20	ns
t ₃	Rise time ^[9] (-1, -2, -3, -4)	Measured between 0.8 V and 2.0 V, 15 pF load	_	_	1.50	ns
t ₃	Rise time ^[9] (-1H, -5H)	Measured between 0.8 V and 2.0 V, 30 pF load	_	_	1.50	ns
t ₄	Fall time ^[9] (-1, -2, -3, -4)	Measured between 0.8 V and 2.0 V, 30 pF load	_	_	2.20	ns
t ₄	Fall time ^[9] (-1, -2, -3, -4)	Measured between 0.8 V and 2.0 V, 15 pF load	_	_	1.50	ns
t ₄	Fall time ^[9] (-1H, -5H)	Measured between 0.8 V and 2.0 V, 30 pF load	_	_	1.25	ns
t ₅	Output to output skew on same Bank [9] (-1, -2, -3, -4)	All outputs equally loaded	_	_	200	ps
	Output to output skew (-1H, -5H)	All outputs equally loaded	_	-	200	ps
	Output Bank A to output Bank B skew (-1, -4, -5H)	All outputs equally loaded	_	_	200	ps
	Output Bank A to output Bank B skew (-2, -3)	All outputs equally loaded	_	_	400	ps
t ₆	Delay, REF rising edge to FBK rising edge ^[9]	Measured at V _{DD} /2	_	0	±250	ps
t ₇	Device to device skew [9]	Measured at V _{DD} /2 on the FBK pins of devices	_	0	700	ps
t ₈	Output slew rate [9]	Measured between 0.8 V and 2.0 V on -1H, -5H device using Test Circuit 2	1	_	_	V/ns
t _J	Cycle to cycle Jitter [9] (-1, -1H, -4, -5H)	load	_	75	200	ps
		Measured at 66.67 MHz, loaded outputs, 30 pF load	-	_	200	ps
		Measured at 133.3 MHz, loaded outputs, 15 pF load	_	_	100	ps
t _J	Cycle to cycle Jitter [9] (-2, -3)	Measured at 66.67 MHz, loaded outputs, 30 pF load	-	_	400	ps
		Measured at 66.67 MHz, loaded outputs, 15 pF load	-	_	400	ps
t _{LOCK}	PLL lock time [9]	Stable power supply, valid clocks presented on REF and FBK pins	-	_	1.0	ms

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Note
9. All parameters are specified with loaded outputs.



Operating Conditions for Industrial Temperature Devices

Parameter	Description	Min	Max	Unit
V_{DD}	Supply voltage	3.0	3.6	V
T _A	Operating temperature (ambient temperature)	-40	85	°C
C_L	Load capacitance, below 100 MHz	_	30	pF
	Load capacitance, from 100 MHz to 133 MHz	_	15	pF
C _{IN}	Input capacitance [10]	_	7	pF
t _{PU}	Power up time for all V_{DDs} to reach minimum specified voltage (power ramps must be monotonic)	0.05	50	ms

Electrical Characteristics for Industrial Temperature Devices

Parameter	Description	Test Conditions	Min	Max	Unit
V _{IL}	Input LOW voltage		_	0.8	V
V _{IH}	Input HIGH voltage		2.0	-	V
I _{IL}	Input LOW current	V _{IN} = 0 V	_	50.0	μΑ
I _{IH}	Input HIGH current	$V_{IN} = V_{DD}$	_	100.0	μΑ
V _{OL}	Output LOW voltage [11, 12]	I _{OL} = 8 mA (-1, -2, -3, -4) I _{OL} = 12 mA (-1H, -5H)	_	0.4	V
V _{OH}	Output HIGH voltage [11, 12]	I _{OH} = -8 mA (-1, -2, -3, -4) I _{OH} = -12 mA (-1H, -5H)	2.4	-	V
I _{DD} (PD mode)	Power down supply current	REF = 0 MHz	-	25.0	μΑ
I _{DD}	Supply current	Unloaded outputs, 100 MHz, Select inputs at V _{DD}	_	45.0	mA
		or GND	_	70 (-1H, -5H)	mA
		Unloaded outputs, 66 MHz REF (-1, -2, -3, -4)	_	35.0	mA
		Unloaded outputs, 66 MHz REF (-1, -2, -3, -4)	_	20.0	mA

^{10.} Applies to both Ref clock and FBK.

11. Parameter is guaranteed by design and characterization. Not 100% tested in production.

12. All parameters are specified with loaded outputs.



Switching Characteristics for Industrial Temperature Devices

Parameter [13]	Description	Test Conditions	Min	Тур	Max	Unit
F _{in}	Input frequency	-	10	_	133.3	MHz
t ₁	Output frequency	30 pF load	10	_	100 (-1, -2, -3, -4) 66.67 (-5H)	MHz
t ₁	Output frequency	20 pF load, -1H, -5H devices	10	_	133.3 (-1H) 66.67 (-5H)	MHz
t ₁	Output frequency	15 pF load, -1, -2, -3, -4 devices	10	_	133.3	MHz
t _{PD}	Duty cycle ^[13, 14] = t ₂ ÷ t ₁ (-1, -2, -3, -4, -1H, -5H)	Measured at 1.4 V, F _{OUT} = 66.66 MHz, 30 pF load	40.0	50.0	60.0	%
t _{PD}	Duty cycle ^[13, 14] = t ₂ ÷ t ₁ (-1, -2, -3, -4, -1H, -5H)	Measured at 1.4 V, F _{OUT} < 50 MHz, 15 pF load	45.0	50.0	55.0	%
t ₃	Rise time [13, 14] (-1, -2, -3, -4)	Measured between 0.8 V and 2.0 V, 30 pF load	_	_	2.50	ns
t ₃	Rise time [13, 14] (-1, -2, -3, -4)	Measured between 0.8 V and 2.0 V, 15 pF load	_	_	1.50	ns
t ₃	Rise time [13, 14] (-1H, -5H)	Measured between 0.8 V and 2.0 V, 30 pF load	_	_	1.50	ns
t ₄	Fall time [13, 14] (-1, -2, -3, -4)	Measured between 0.8 V and 2.0 V, 30 pF load	_	_	2.50	ns
t ₄	Fall time [13, 14] (-1, -2, -3, -4)	Measured between 0.8 V and 2.0 V, 15 pF load	_	_	1.50	ns
t ₄	Fall time [13, 14] (-1H, -5H)	Measured between 0.8 V and 2.0 V, 30 pF load	_	_	1.25	ns
t ₅	Output to output skew on same Bank [13, 14] (-1, -2, -3, -4)	All outputs equally loaded	_	-	200	ps
	Output to output skew (-1H, -5H)	All outputs equally loaded	_	_	200	ps
	Output Bank A to output Bank B skew (-1, -4, -5H)	All outputs equally loaded	_	_	200	ps
	Output Bank A to output Bank B skew (-2, -3)	All outputs equally loaded	_	_	400	ps
t ₆	Delay, REF rising edge to FBK rising edge [13, 14]	Measured at V _{DD} /2	_	0	±250	ps
t ₇	Device to device skew [13, 14]	Measured at V _{DD} /2 on the FBK pins of devices	_	0	700	ps
t ₈	Output slew rate [13, 14]	Measured between 0.8 V and 2.0 V on -1H, -5H device using Test Circuit 2	1	_	_	V/ns
t _J	Cycle to cycle Jitter [13, 14] (-1, -1H, -4, -5H)	Measured at 66.67 MHz, loaded outputs, 15 pF load	_	75	200	ps
		Measured at 66.67 MHz, loaded outputs, 30 pF load	_	_	200	ps
		Measured at 133.3 MHz, loaded outputs, 15 pF load	_	_	100	ps
t _J	Cycle to cycle Jitter [13, 14] (-2, -3)	Measured at 66.67 MHz, loaded outputs, 30 pF load	-	-	400	ps
		Measured at 66.67 MHz, loaded outputs, 15 pF load	-	-	400	ps
t _{LOCK}	PLL lock time [13, 14]	Stable power supply, valid clocks presented on REF and FBK pins	_	_	1.0	ms

^{13.} All parameters are specified with loaded outputs.14. Parameter is guaranteed by design and characterization. Not 100% tested in production.



Switching Waveforms

Figure 3. Duty Cycle Timing

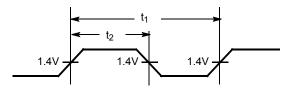


Figure 4. All Outputs Rise/Fall Time

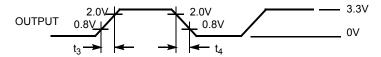


Figure 5. Output-Output Skew

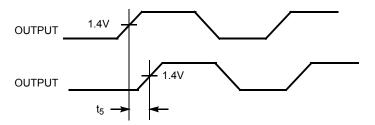


Figure 6. Input-Output Propagation Delay

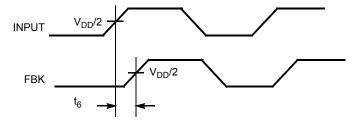
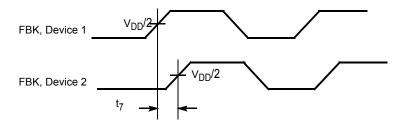


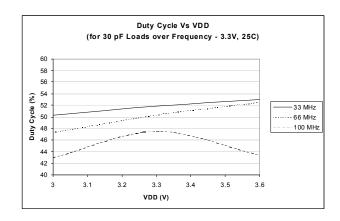
Figure 7. Device-Device Skew

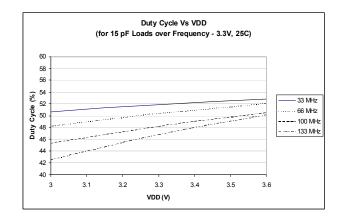


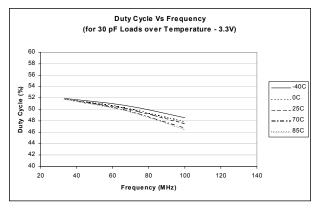


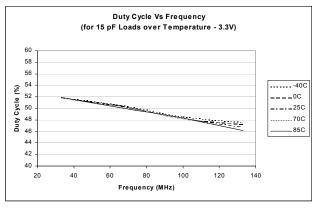
Typical Duty Cycle and I_{DD} Trends

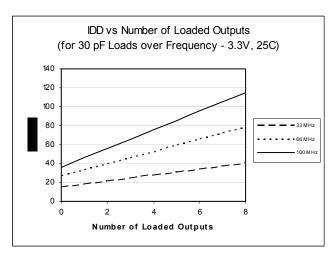
For CY2308-1, 2, 3, 4 $^{[15, 16]}$

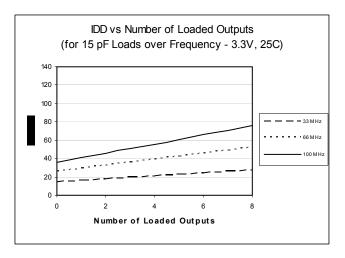












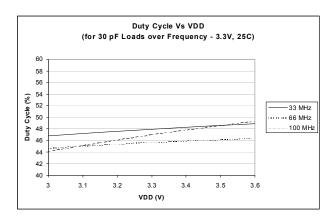
^{15.} Duty cycle is taken from typical chip measured at 1.4 V.

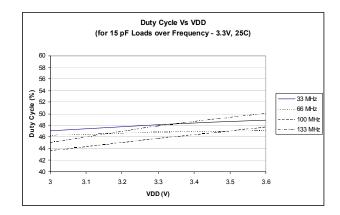
^{16.} I_{DD} data is calculated from I_{DD} = I_{CORE} + nCVf, where I_{CORE} is the unloaded current. (n = number of outputs; C = Capacitance load per output (F); V = Voltage supply (V); f = frequency (Hz).

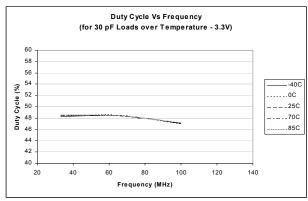


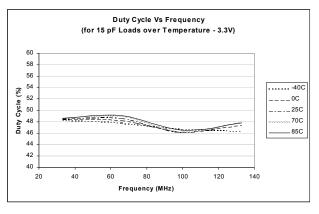
Typical Duty Cycle and I_{DD} Trends

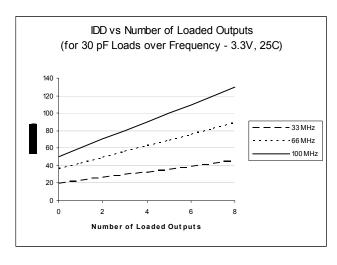
For CY2308-1H, 5H [17, 18]

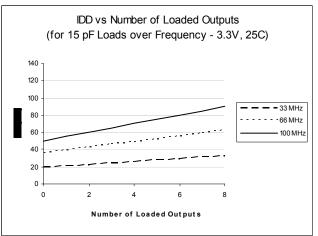










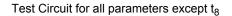


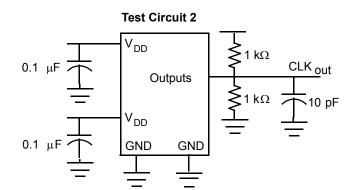
- 17. Duty cycle is taken from typical chip measured at 1.4 V.
- 18. I_{DD} data is calculated from I_{DD} = I_{CORE} + nCVf, where I_{CORE} is the unloaded current. (n = number of outputs; C = Capacitance load per output (F); V = Voltage supply (V); f = frequency (Hz).



Test Circuits

Test Circuit 1 0.1 μ F Outputs VDD Outputs CLKOUT CLOAD On μ F GND GND GND GND GND GND





Test Circuit for t_8 , Output slew rate on -1H, -5H device



Ordering Information

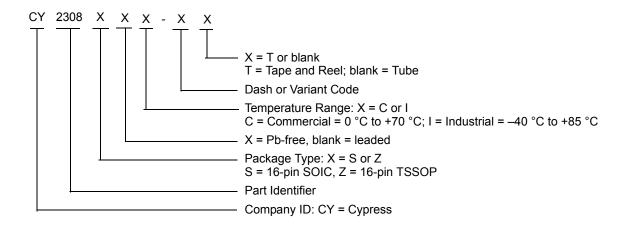
Ordering Code	Package Type	Operating Range	
CY2308SI-1T [19]	16-pin SOIC – Tape and Reel	Industrial	
CY2308ZI-1H [19]	16-pin TSSOP	Industrial	
CY2308ZI-1HT [19]	16-pin TSSOP – Tape and Reel	Industrial	
CY2308SI-2 ^[19]	16-pin SOIC	Industrial	
CY2308SI-2T [19]	16-pin SOIC – Tape and Reel	Industrial	
Pb-free		1	
CY2308SXC-1	16-pin SOIC	Commercial	
CY2308SXC-1T	16-pin SOIC – Tape and Reel	Commercial	
CY2308SXI-1	16-pin SOIC	Industrial	
CY2308SXI-1T	16-pin SOIC – Tape and Reel	Industrial	
CY2308SXC-1H	16-pin SOIC	Commercial	
CY2308SXC-1HT	16-pin SOIC – Tape and Reel	Commercial	
CY2308SXI-1H	16-pin SOIC	Industrial	
CY2308SXI-1HT	16-pin SOIC – Tape and Reel	Industrial	
CY2308ZXC-1H	16-pin TSSOP	Commercial	
CY2308ZXC-1HT	16-pin TSSOP – Tape and Reel	Commercial	
CY2308ZXI-1H	16-pin TSSOP	Industrial	
CY2308ZXI-1HT	16-pin TSSOP – Tape and Reel	Industrial	
CY2308SXC-2	16-pin SOIC	Commercial	
CY2308SXC-2T	16-pin SOIC – Tape and Reel	Commercial	
CY2308SXI-2	16-pin SOIC	Industrial	
CY2308SXI-2T	16-pin SOIC – Tape and Reel	Industrial	
CY2308SXC-3	16-pin SOIC	Commercial	
CY2308SXC-3T	16-pin SOIC – Tape and Reel	Commercial	
CY2308SXI-3	16-pin SOIC	Industrial	
CY2308SXI-3T	16-pin SOIC – Tape and Reel	Industrial	
CY2308SXC-4	16-pin SOIC	Commercia	
CY2308SXC-4T	16-pin SOIC – Tape and Reel	Commercial	
CY2308SXI-4	16-pin SOIC	Industrial	
CY2308SXI-4T	16-pin SOIC – Tape and Reel	Industrial	

Note

^{19.} Not recommended for new designs.



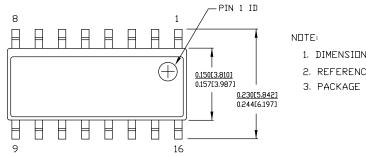
Ordering Code Definitions





Package Diagrams

Figure 8. 16-pin SOIC (150 Mil) S16.15/SZ16.15 Package Outline, 51-85068

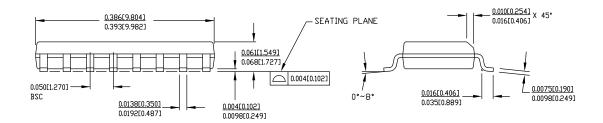


1. DIMENSIONS IN INCHESIMM] MANK.

2. REFERENCE JEDEC MS-012

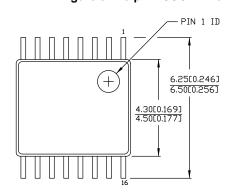
3. PACKAGE WEIGHT : refer to PMDD spec. 001-04308

PART #		
	STANDARD PKG.	
SZ16.15	LEAD FREE PKG.	



51-85068 *E

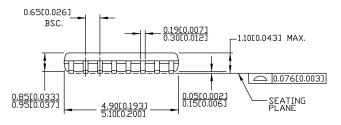
Figure 9. 16-pin TSSOP 4.40 mm Body Z16.173 Package Outline, 51-85091

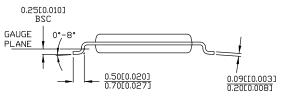


DIMENSIONS IN MMEINCHESI MIN. MAX.

REFERENCE JEDEC MO-153
PACKAGE WEIGHT 0.05gms

PART #		
Z16.173	STANDARD PKG.	
ZZ16.173	LEAD FREE PKG.	





51-85091 *D



Acronyms

Table 1. Acronyms Used in this Document

Acronym	Description	
FBK	Feedback	
PLL	Phase Locked Loop	
MUX	Multiplexer	

Document Conventions

Units of Measure

Table 2. Units of Measure

Symbol	Unit of Measure	Symbol	Unit of Measure
°C	degrees Celsius	μW	microwatt
dB	decibels	mA	milliampere
fC	femtocoulomb	mm	millimeter
fF	femtofarad	ms	millisecond
Hz	hertz	mV	millivolt
KB	1024 bytes	nA	nanoampere
Kbit	1024 bits	ns	nanosecond
kHz	kilohertz	nV	nanovolt
kΩ	kilohm	Ω	ohm
MHz	megahertz	pA	picoampere
ΜΩ	megaohm	pF	picofarad
μA	microampere	рр	peak-to-peak
μF	microfarad	ppm	parts per million
μΗ	microhenry	ps	picosecond
μs	microsecond	sps	samples per second
μV	microvolt	σ	sigma: one standard deviation
μVrms	microvolts root-mean-square		



Document History Page

Document Title: CY2308, 3.3 V Zero Delay Buffer Document Number: 38-07146					
Rev.	ECN	Orig. of Change	Submission Date	Description of Change	
**	110255	SZV	12/17/01	Changed from Specification number: 38-00528 to 38-07146	
*A	118722	RGL	10/31/02	Added Note 4.	
*B	121832	RBI	12/14/02	Power up requirements added to Operating Conditions Information	
*C	235854	RGL	06/24/04	Added Pb-free Devices	
*D	310594	RGL	02/09/05	Removed obsolete parts in the ordering information table Specified typical value for cycle-to-cycle jitter	
*E	1344343	KVM / VED	08/20/07	Brought the Ordering Information Table up to date: removed three obsolete parts and added two parts Changed titles to tables that are specific to commercial and industrial temperature ranges	
*F	2568575	AESA	09/19/08	Updated template. Added Note 19 "Not recommended for new designs." Changed IDD (PD mode) from 12.0 to 25.0 μ A for Commercial and Industria Temperature Devices Deleted Duty Cycle parameters for F _{out} < 50 MHz Removed CY2308SI-4, CY2308SI-4T and CY2308SC-5HT.	
*G	2632364	KVM	01/08/09	Corrected TSSOP package size (from 150 mil to 4.4 mm) in Ordering Information table	
*H	2673353	KVM / PYRS	03/13/09	Reverted I _{DD} (PD mode) and Duty Cycle parameters back to the values in revision *E: Changed I _{DD} (PD mode) from 25 to 12 μ A for commercial temperature device. Added Duty Cycle parameters for F _{out} < 50 MHz for commercial and industria devices.	
*	2897373	CXQ	03/22/10	Updated Ordering Information. Updated Package Diagrams. Updated copyright section.	
*`	2971365	BASH	07/06/10	Updated input to output skew and power down current number in Functional Description, page 1 Update pin descriptions in 'Pin Description' column, Table1, page 2 Added 'Input Frequency' parameter and output frequency for -1H and -5H in 'Switching Characteristics Table' and removed footnote, page 4, 5, and 7. Modified Description on page 1 and page 3 to make clear that user has to select one of the outputs to drive feedback. Added footnote in 'Available CY2308 Configurations' Table, page 3, for clarification.	
*K	3047133	CXQ	10/04/2010	Sunset Review. No change to data sheet from last revision.	
*L	3055192	CXQ	10/11/2010	Updated Ordering Information (Removed part CY2308SXI-5H and CY2308SXI-5HI).	
*M	3402187	BASH	10/11/2011	Updated Ordering Information (Removed prune part numbers CY2308SI-1H and CY2308SI-1HT). Updated Package Diagrams. Updated in new template.	
*N	4128657	CINM	10/23/2013	Updated Package Diagrams: spec 51-85068 – Changed revision from *D to *E. Updated in new template.	
				Completing Sunset Review.	



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